


# Multilayer Ceramic Chip Capacitors

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## C2012C0G1V273K060AC

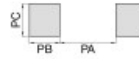
**TDK item description** ? C2012C0G1V273KT\*\*\*\*

**Applications**  Commercial Grade

**Feature** General General (Up to 75V)

**Series** C2012 [EIA 0805]

**Status**  Production (Not Recommended for New Design)




● ●  
Images are for reference only and show exemplary products.



PDF file of this page 

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### Documents

-  Catalog Update
-  Specification
-  RoHS Certificate Update
-  SVHC/REACH Certificate
-  Sample Kits

### Pages related to the series to which this product belongs

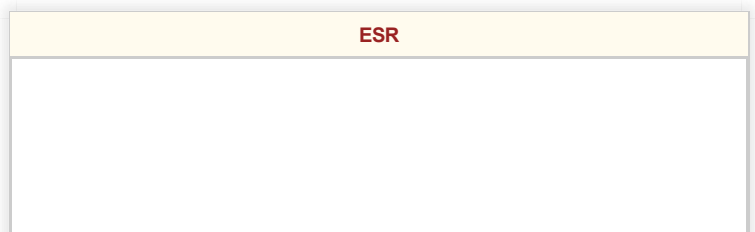
-  Description of icons | Environment

Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	0.60mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	27nF ±10%
Rated Voltage	35VDC
Temperature Characteristic <span>?</span>	COG(0±30ppm/°C)
Q (Min.)	1000
Insulation Resistance (Min.)	10000MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

## Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)



no data available

no data available

Configuration

Configuration

**Capacitance**

no data available

**DC Bias Characteristic**

no data available

Configuration

Configuration

**Temperature Characteristic**

no data available

**Ripple Temperature Rising**

no data available

Configuration

Configuration



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- Ferrites and Accessories >
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